

ABSTRACT

To enable to downsize a package for containing a solid-state imaging element relative to a solid-state imaging element having the same size and accordingly, downsize a solid-state imaging device for containing the solid-state imaging element thereto, further, downsize an apparatus such as a video camera or a still camera using the solid-state imaging device, there is provided a package for containing semiconductor element comprising a package having a recess portion for containing a semiconductor element, and a pair of positioning holes and a pair of attaching holes respectively provided at a pair of opposed side portions of the recess portion at surfaces of the package, wherein a line connecting the pair of positioning holes and a line connecting the pair of attaching holes are intersected with each other substantially at a center of the package.